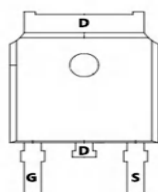


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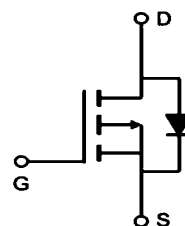
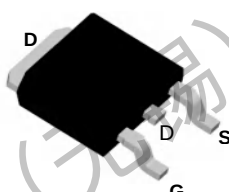
P-Channel Enhancement Mosfet

General Description • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant Applications • Load switch • PWM	General Features $V_{DS} = -100V$ $I_D = -15A$ $R_{DS(ON)} = 135 m\Omega (typ.) @ V_{GS} = -10V$ 100% UIS Tested 100% R_g Tested 
--	--

D:TO-252-3L



Marking:15P10



Absolute Maximum Ratings ($T_C = 25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V$	-15	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V$	-6.5	A
I_{DM}	Pulsed Drain Current	-40	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	54	W
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 175	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	2.3	$^\circ C/W$



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P-Channel Enhancement Mosfet

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250 μ A	-100	---	---	V
	BV _{DSS} Temperature Coefficient	Reference to 25 °C ID=-1mA	---	---	---	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} =0V, V _{DS} =-100V T _J =25°C	---	---	-1	μ A
I _{GSS}	Gate-Source Leakage Current	V _{GS} =± 20V, V _{DS} =0A	---	---	± 100	nA
On Characteristics						
V _{GS(th)}	GATE-Source Threshold Voltage	V _{GS} =V _{DS} , I _D =-250 μ A	-1	-2	-3	V
R _{DS(ON)}	Drain-Source On Resistance	V _{GS} =-10V, I _D =-5A	---	135	150	m Ω
		V _{GS} =-4.5V, I _D =-2A	---	---	---	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =-25V, V _{GS} =0V, f=1MHz	---	1419	2500	pF
C _{oss}	Output Capacitance		---	89	170	
C _{rss}	Reverse Transfer Capacitance		---	45	90	
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} =-50V, I _D =-5A, R _{GEN} =25 Ω ,V _{GS} =-10V	---	18	36	ns
t _r	Rise Time		---	8	16	ns
t _{d(off)}	Turn-Off Delay Time		---	100	200	ns
t _f	Fall Time		---	30	60	ns
Q _g	Total Gate Charge	V _{GS} =-10V, V _{DS} =-80V,	---	20	40	nC
Q _{gs}	Gate-Source Charge	I _D =-5A	---	3.5	7	nC
Q _{gd}	Gate-Drain “Miller” Charge		---	4.6	9	nC
Drain-Source Diode Characteristics						
V _{SD}	Source-Drain Diode Forward Voltage	V _{GS} =0V, I _S =-1A, T _J =25°C	---	---	-1.2	V
I _S	Diode Forward Current		---	---	-15	A
T _{rr}	Reverse Recovery Time	V _{GS} =0V, I _S =-5A , di/dt=100A/μs	---	26.6	---	NS
Q _{rr}	Reverse Recovery Charge	T =25°C	---	24.2	---	NC

Typical Characteristics: ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

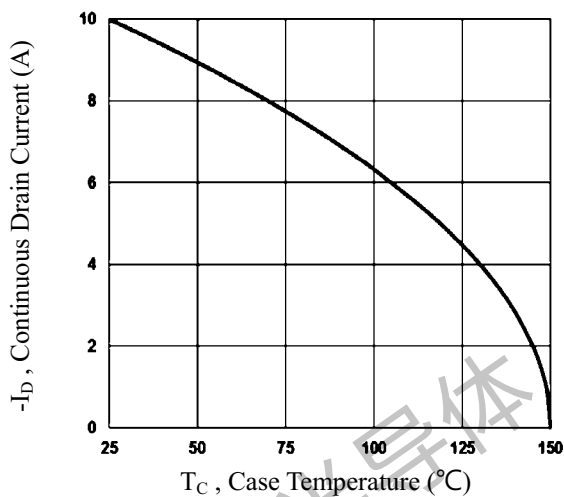


Fig.1 Continuous Drain Current vs. T_C

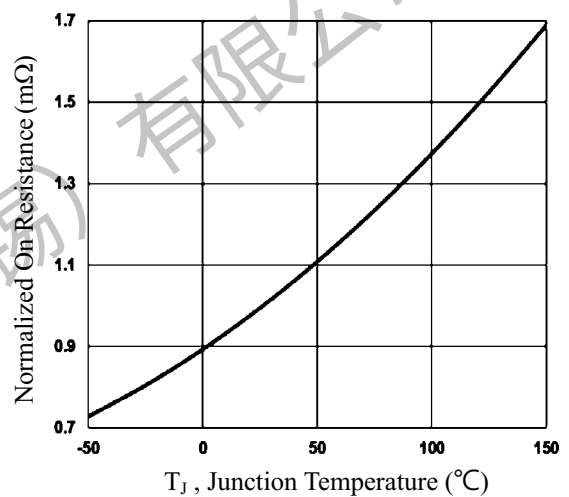


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

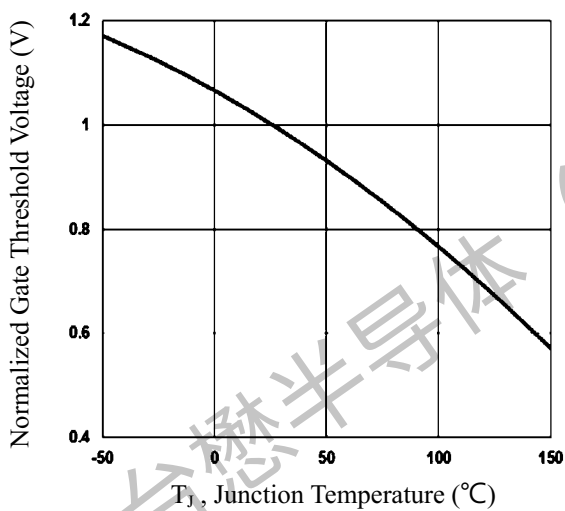


Fig.3 Normalized V_{th} vs. T_J

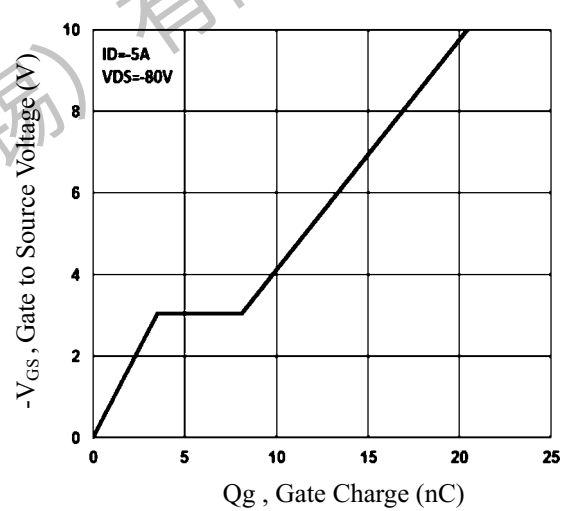


Fig.4 Gate Charge Waveform

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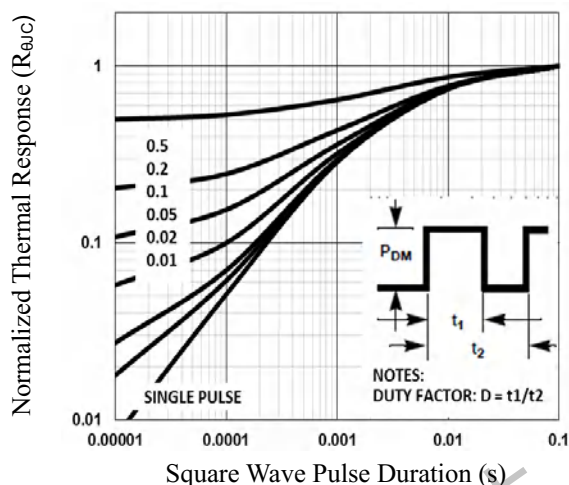


Fig.5 Normalized Transient Impedance

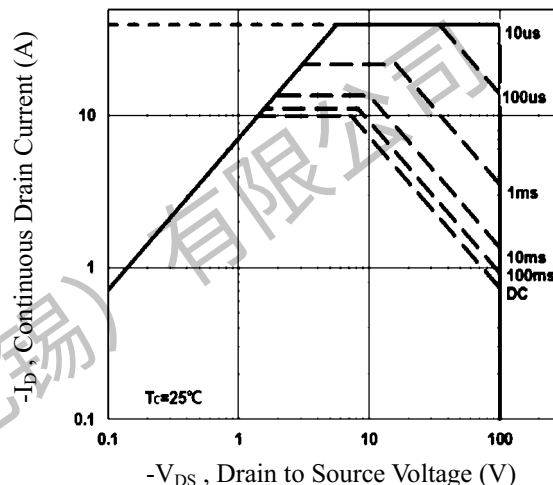
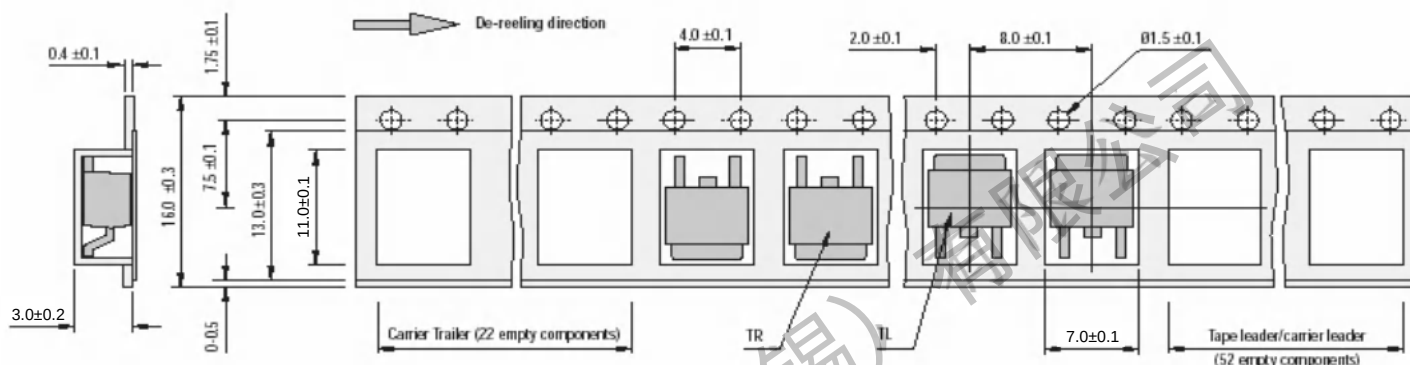


Fig.6 Maximum Safe Operation Area

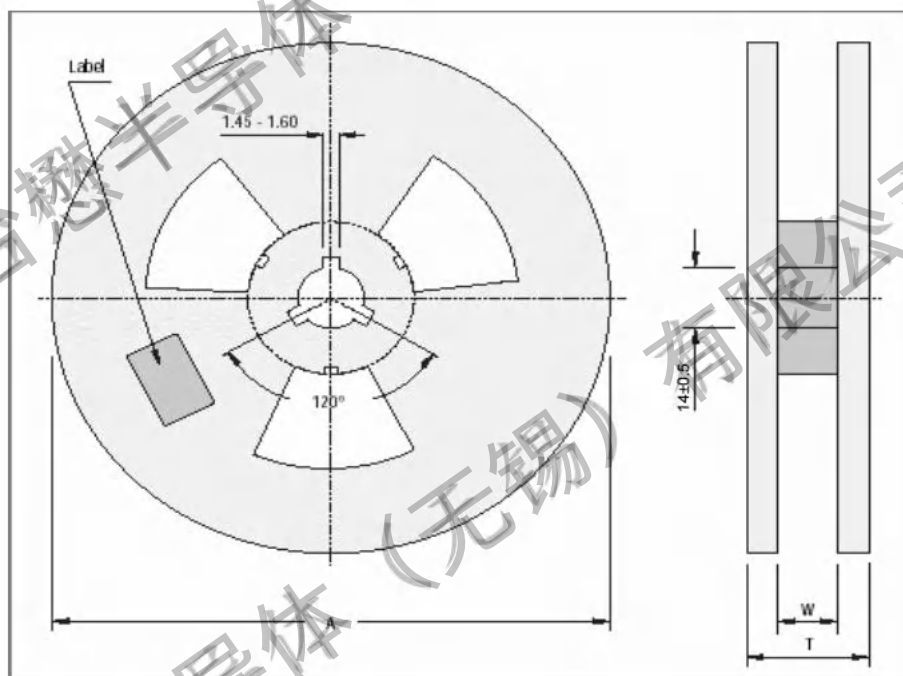
TM15P10D

P-Channel Enhancement Mosfet

TO-252-3L Embossed Carrier Tape



TO-252-3L Reel



All Dimensions are in mm.

Reel Specifications				
Package	Tape Width	Reel Dia. A - Max	Inside Thickness W	Reel Thickness T - max
TO-252-3L	16	330	18.0 ± 1.5	20

Packaging Information

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
2,500 pcs	13 inch	5,000 pcs	355×370×50	25,000 pcs	380×275×380	

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Revision history:

Date	Rev	Description	Page
2023.04.21	23.04	Original	